Title: Datasheet for CC2564MODN Customer Contact: PCN Manager Change Type: Assembly Site Assembly Site Assembly Process Assembly Process Assembly Materials Assem	PCN Number:	20160216000		1	DCN D		2/10/2016	
Customer Contact: PCN Manager Dept: Quality Services					PCN Date		le: 3/19/2016	
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Assembly Process Assembly Materials Part number change Wafer Bump Material Parking/Shipping/Labeling Test Site Wafer Fab Materials Wafer Bump Materials Wafer Bump Materials Wafer Bump Materials Wafer Fab Materials Wafer Bump Materials Wafer Fab Materials Wafer Fab Materials Wafer Bump Materials Wafer Bump Materials Wafer Bump Materials Wafer Bump Materials Wafer Fab Materials Wafer Bump Materials Wafer Bum			Docian		Mafor	Rum	n Cito	
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Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. PEXAS CC2564MODA INSTRUMENTS Changes from Revision C (November 2015) to Revision D Page Added CC2564MIODA device variant Added applications in Section 1.2, Applications Changed VBAT to VDD_IN Figure 5-1 and Figure 5-2 Changed storage temperature range in Section 4.1, Absolute Maximum Ratings. Changed restrictions on verification of parameters in Section 4.7 4.1, Bluetooth BR/EDR RF Partomance. 14 Changed restrictions on verification of parameters in Section 4.7 4.1, Bluetooth BR/EDR RF Partomance. 15 Changed values for Adjacent channel power M-N = 2 and Adjacent channel power M-N > 2 in Section 4.7.4.2.2, Bluetooth E.F Partomance. 16 Changed value of A.7.4.2.3, Bluetooth E.F Partomance. 17 Added 'Includes a 128-bit hardware encryption accelerator as defined by the Bluetooth specifications' in Section 5.4, Bluetooth BR/EDR Description. 18 Changed Figure 5-1 Changed Figure 5-1 Changed Figure 5-1 Section 5.4, Bluetooth BR/EDR Description. Section 5.4, Bluetooth BR/ED			Test Process					
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS CC2564MODN, CC2564MODA SWRS1800 → FEBRUARY 2014 → REVISED DECEMBER 2015 Changes from Revision C (November 2015) to Revision D Added CC2564MODA device variant Added applications in Section 1.2, Applications Changed storage temperature range in Section 4.1, Absolute Maximum Ratings Changed storage temperature range in Section 4.1, Absolute Maximum Ratings Changed storage temperature range in Section 4.7.4.1, Bluetooth BR/EDR RF Performance. Changed restrictions on verification of parameters in Section 4.7.4.2, Bluetooth ERF Performance. Changed restrictions on verification of parameters in Section 4.7.4.2, Bluetooth ERF Performance. Changed restrictions on verification of parameters in Section 4.7.4.2, Bluetooth ERF Performance. Changed restrictions on verification of parameters in Section 4.7.4.1, Bluetooth BR/EDR Performance. 16 Changed restrictions on verification of parameters in Section 4.7.4.2, Bluetooth ERF Performance. 16 Changed values for Adjacent channel power M-N ≥ 2 and Adjacent channel power M-N ≥ 2 in Section 4.7.4.2, Bluetooth ERF Performance. 16 Changed values for Adjacent channel power M-N ≥ 2 and Adjacent channel power M-N ≥ 2 in Section 4.7.4.2, Bluetooth ERF Performance. 16 Changed Fligure 5-10 Changed Fligure 5-11 Change Fligure 5-12 Changed Fligure 5-12 Changed Fligure 5-13 Changed Fligure 5-13 Changed Fligure 5-14 Change Fligure 5-15 Changed Fligure 5-15 Changed Fligure 5-10 Change Fligure 5-10 SWRS160D These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/CC2564MODN Reason for Change: To more accurately reflect device characteristics. Anticipated impact. This is a specification change announcement onl				Wafer				
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. **Texas** Cc2564MODA C			tification Details	5				
The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS TEXAS CC2564MODN, CC2564MODA SWRS1600_FEBRUARY 2014_REVISED DECEMBER 2015 Changes from Revision C (November 2015) to Revision D Added CC2564MODA device variant Added applications in Section 1.2, Applications Changed VBAT to VDD_IN Figure 5-1 and Figure 5-2 Changed storage temperature range in Section 4.7, Absolute Maximum Retings Changed restrictions on verification of parameters in Section 4.7.4.1, Bluetooth BR/EDR RF Performance 14 Changed restrictions on verification of parameters in Section 4.7.4.1, Bluetooth ERF Performance 16 Changed values for Adjacent channel power IM-NI = 2 and Adjacent channel power IM-NI > 2 in Section 4.7.4.2 Bluetooth ER FR Performance 16 Added "Includes a 128-bit hardware encryption accelerator as defined by the Bluetooth specifications" in Section 5.4, Bluetooth BR/EDR Description Changed Figure 5-10 Changed Figure 5-10 Changed Figure 5-10 Changed Section 6.2.2.1, CC2564MODN Reference Design Device Family Change From: Change To: CC2564MODN CC2564MODN CC2564MODN Changes To Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: None.								
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